

Fusion switch concept addresses the cost-performance dilemma in EV powertrains

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Infineon Technologies AG

Motivation

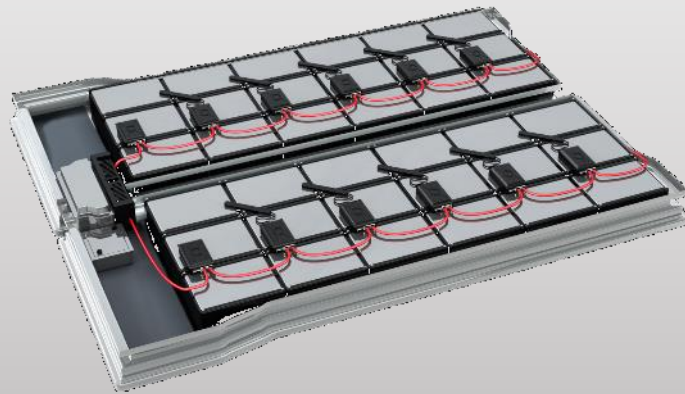
The Cost-Performance Dilemma in EV powertrains

Cost qualitative
(not to scale)

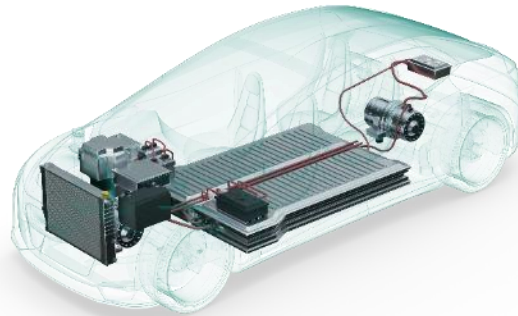


Today's Cost Line

Battery Cost



Electric Vehicles 470V
Compact to SUV class



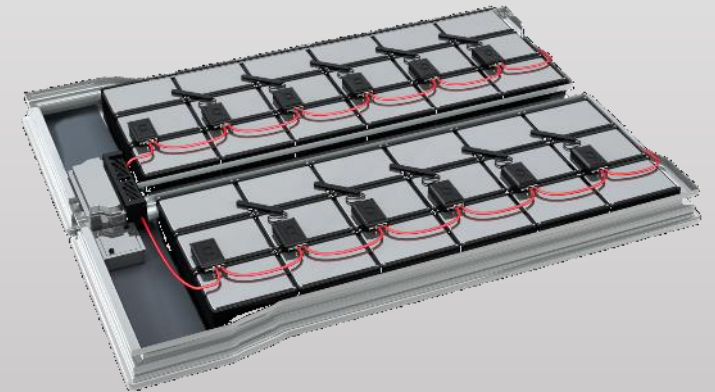
Driving Range 150 .. 600 km

SiC MOSFET power module



Lower power module cost & performance has to be paid by additional battery cost!

Battery Cost



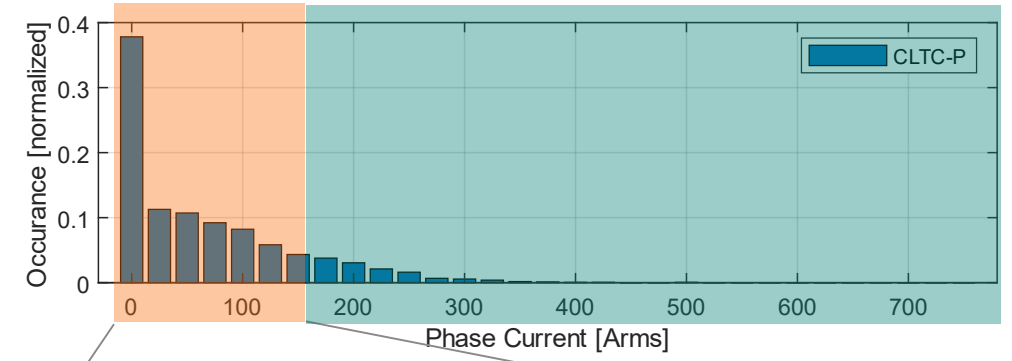
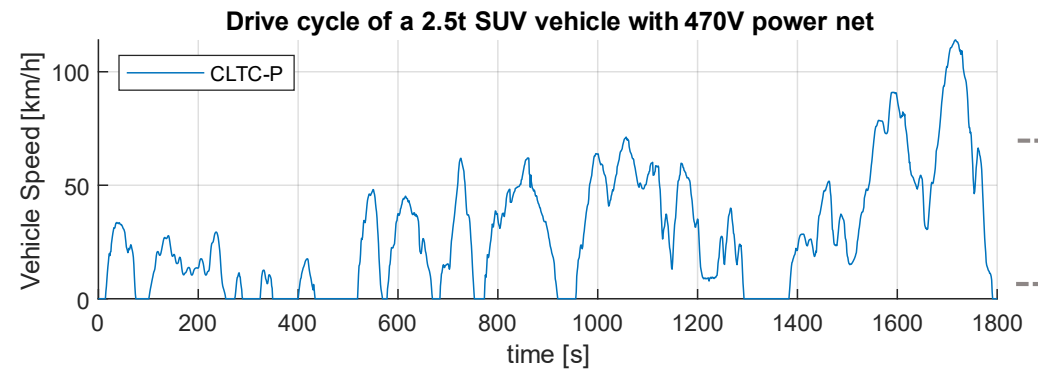
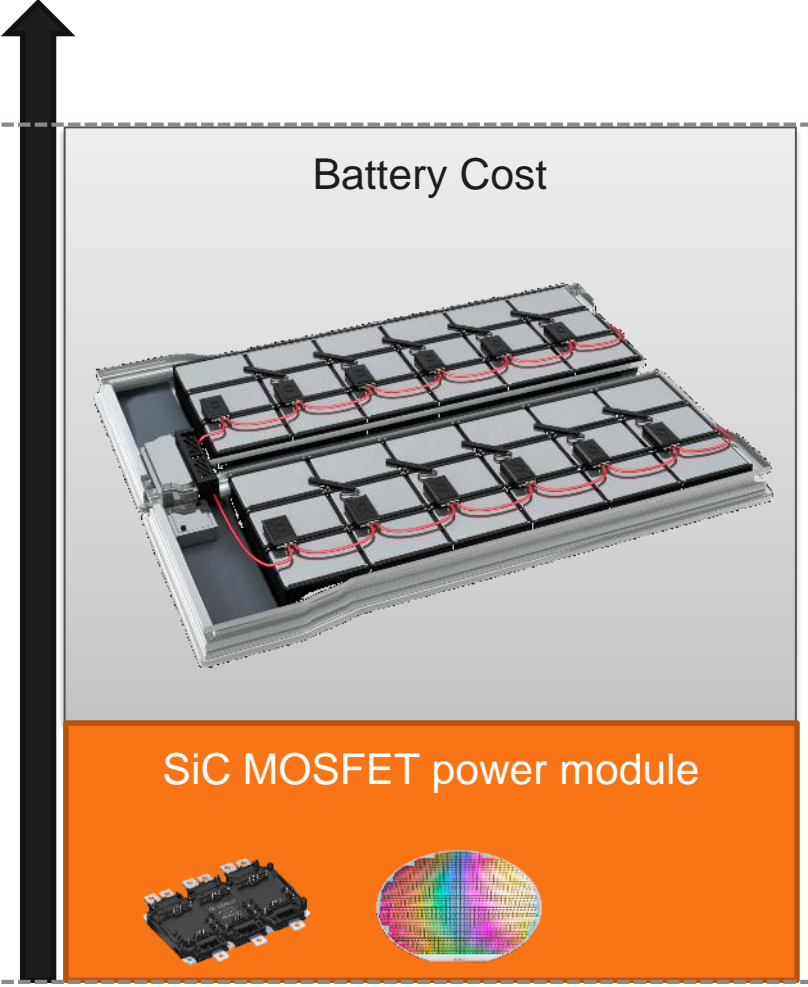
IGBT power module



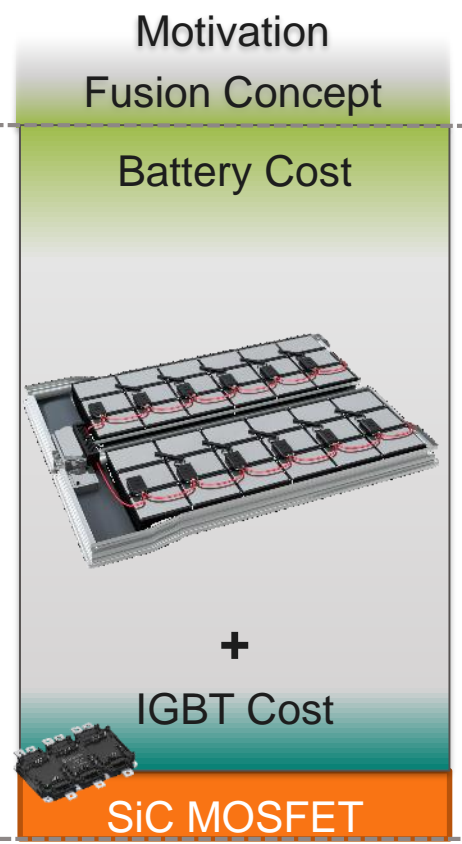
Motivation

Fusion Concept to address cost savings at high efficiency

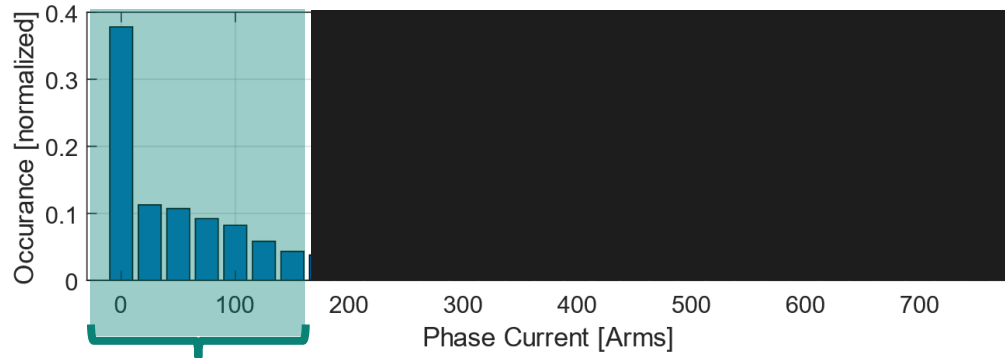
Cost qualitative
(not to scale)



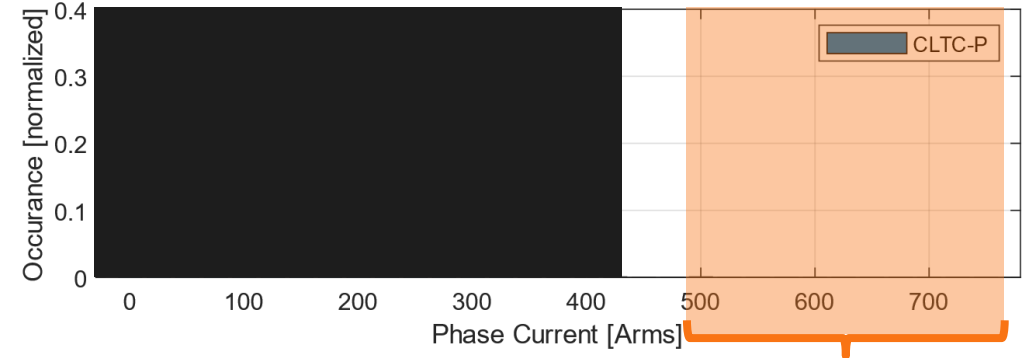
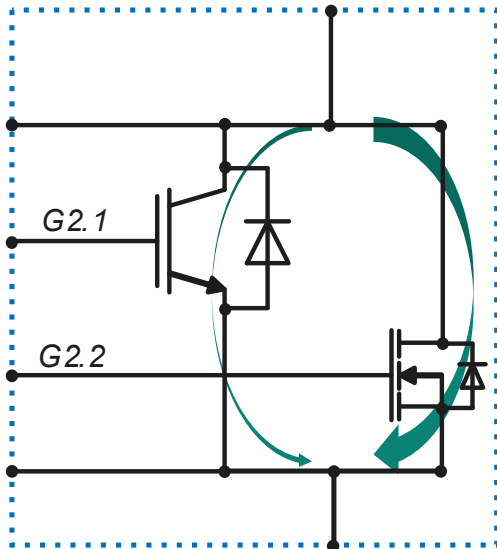
Only 30% of SiC chip content needed to drive the common operating conditions.



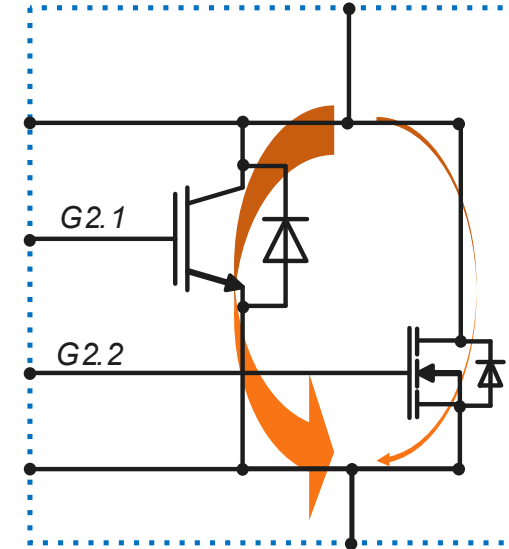
Fusion Switch Concept Requirements for Current Sharing



Light Load



Full Load

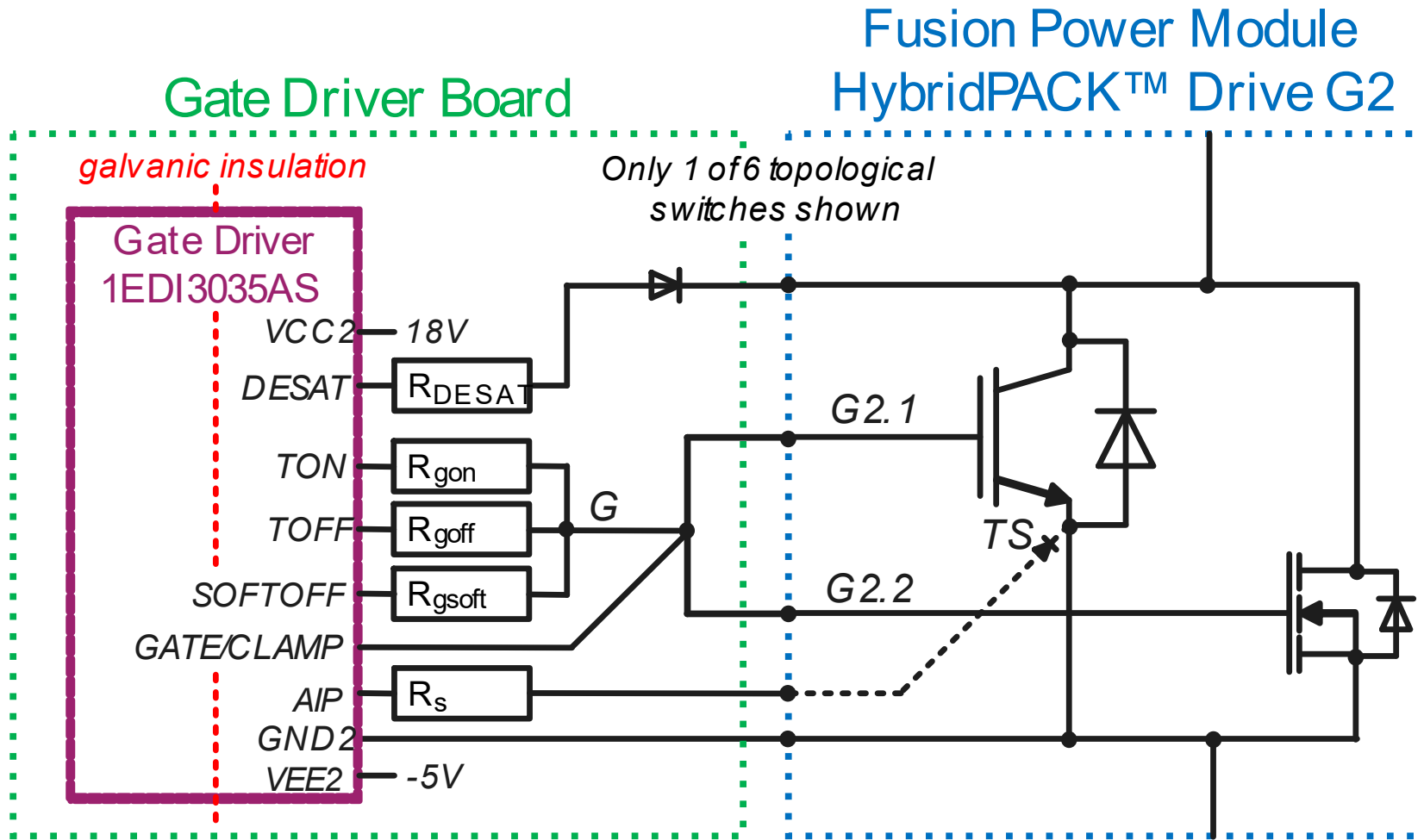


Driving the full current via the small SiC MOSFET area can lead to failure!

Boundary Condition:
A complex control is not intended in high volume automotive applications!

Fusion Switch with Single Gate Drive

Makes it ready for high volume automotive applications



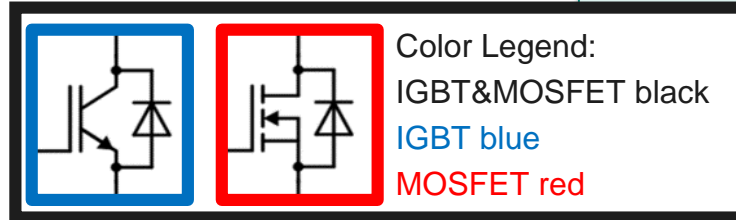
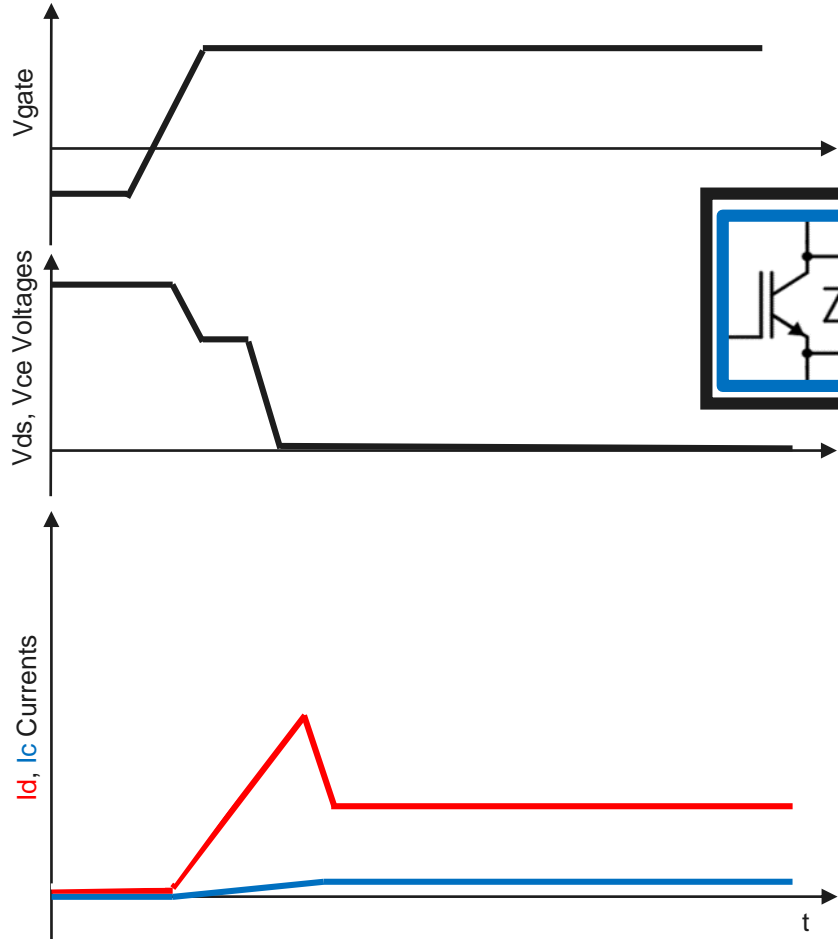
The Fusion switch concept is motivated by using a standard single gate drive.

The IGBT | Diode | SiC MOSFET characteristics and power module layout has to support the required current sharing task.

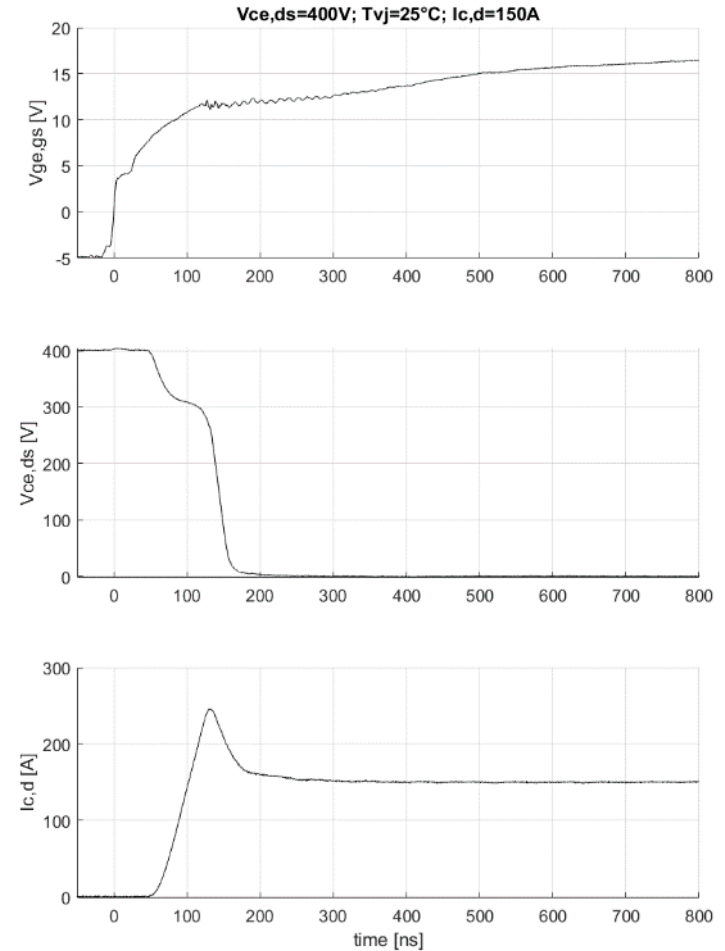
Fusion Switch with Single Gate Drive

Turn-on at light load

Basic Principle (simplified)



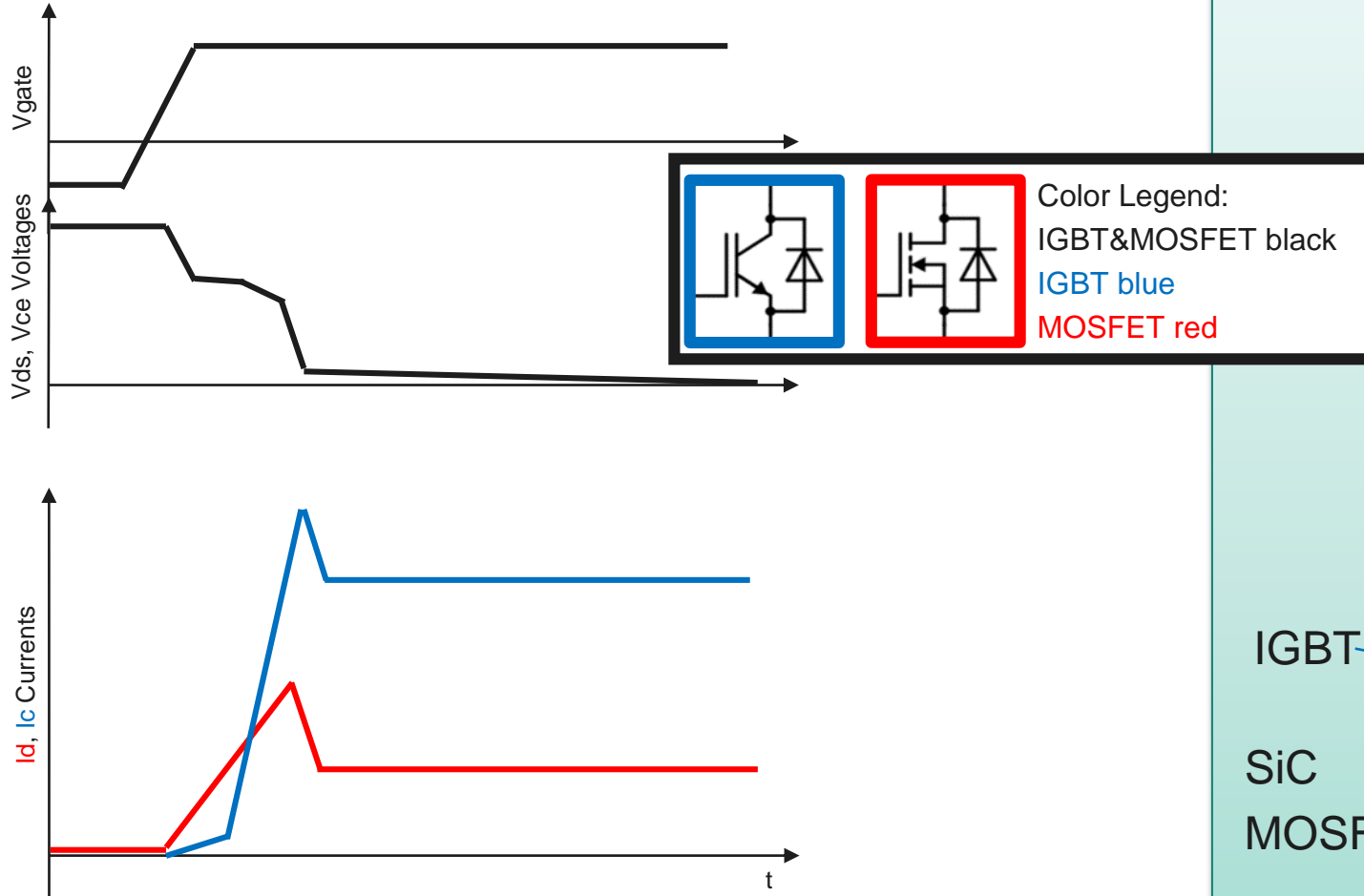
Measured



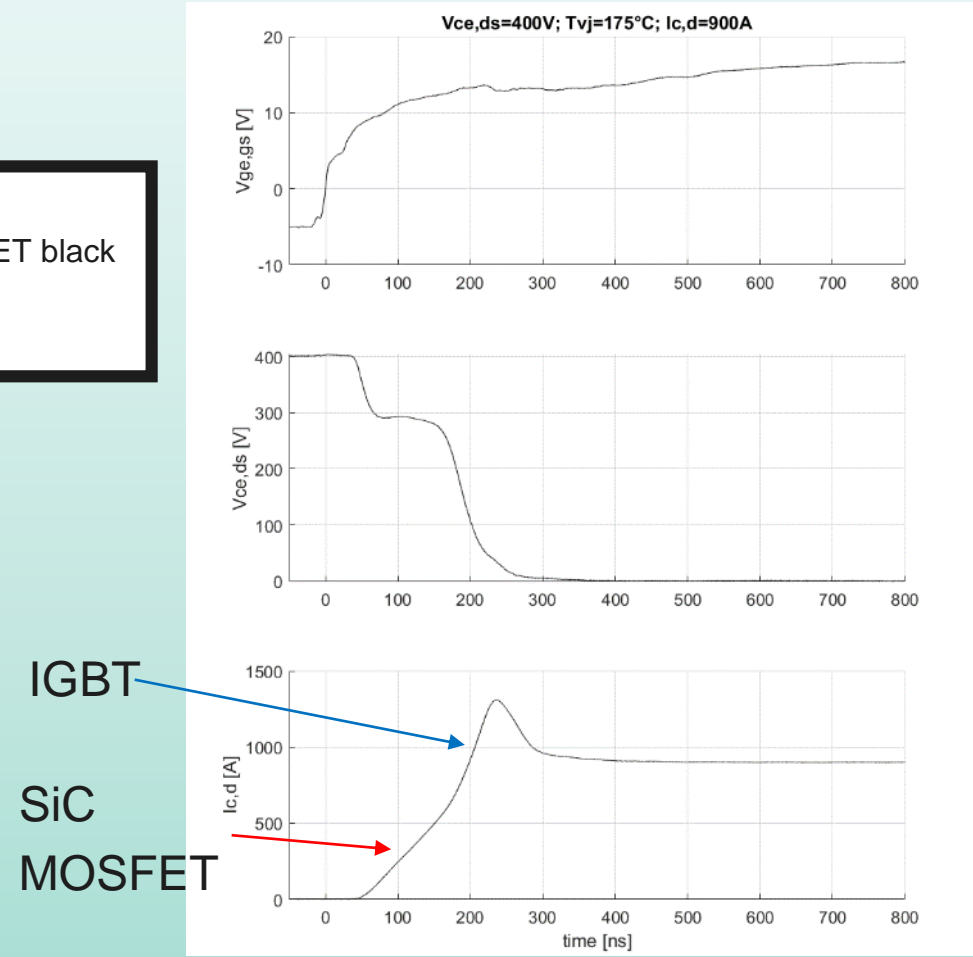
Fusion Switch with Single Gate Drive

Turn-on at full load

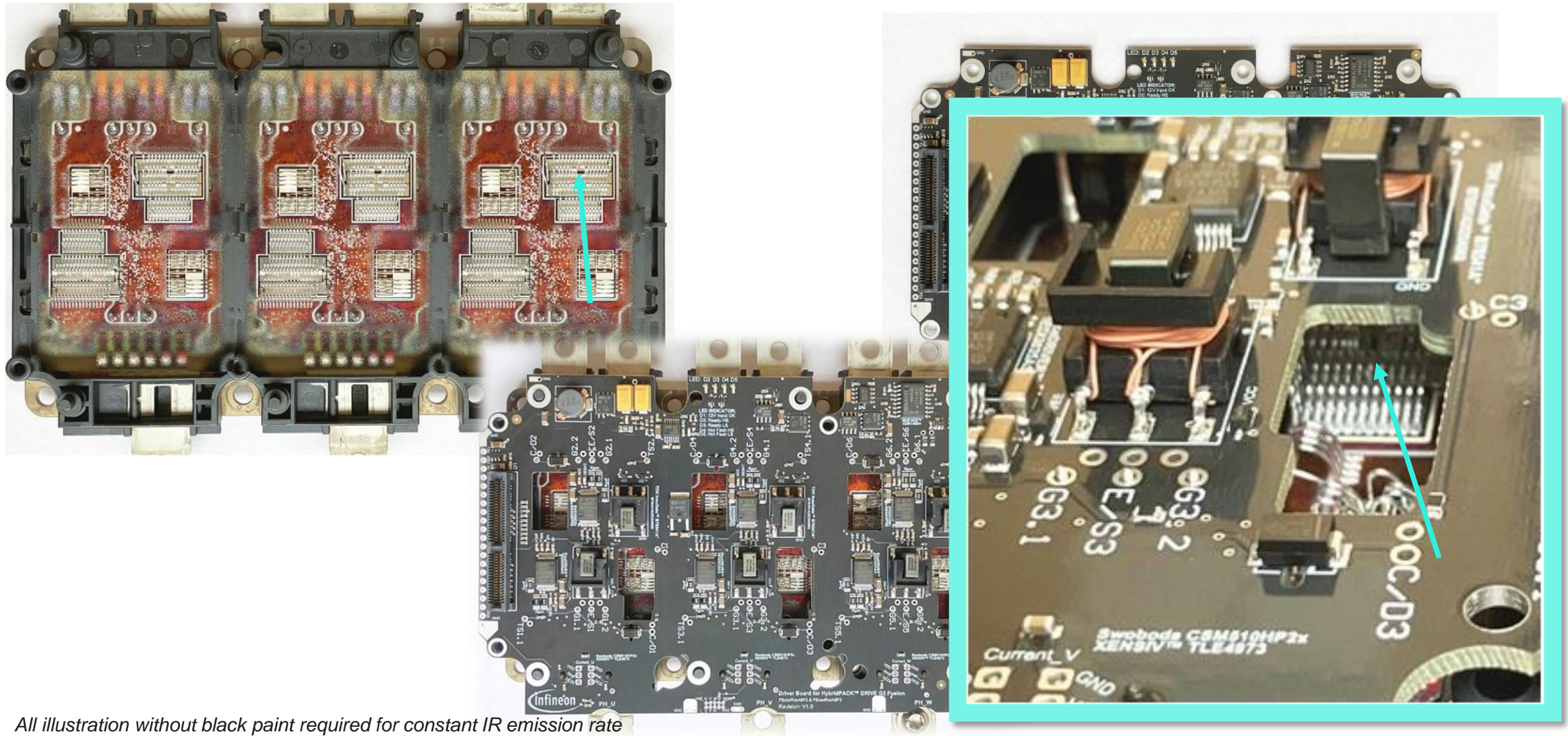
Basic Principle (simplified)



Measured



Fusion Switch Concept Thermal Testing Setup for Thermal IR Testing during Inverter Operation



All illustration without black paint required for constant IR emission rate

Fusion Switch Concept Thermal Testing

Inverter Thermal IR Testing @400V, 10kHz and 65°C coolant fluid

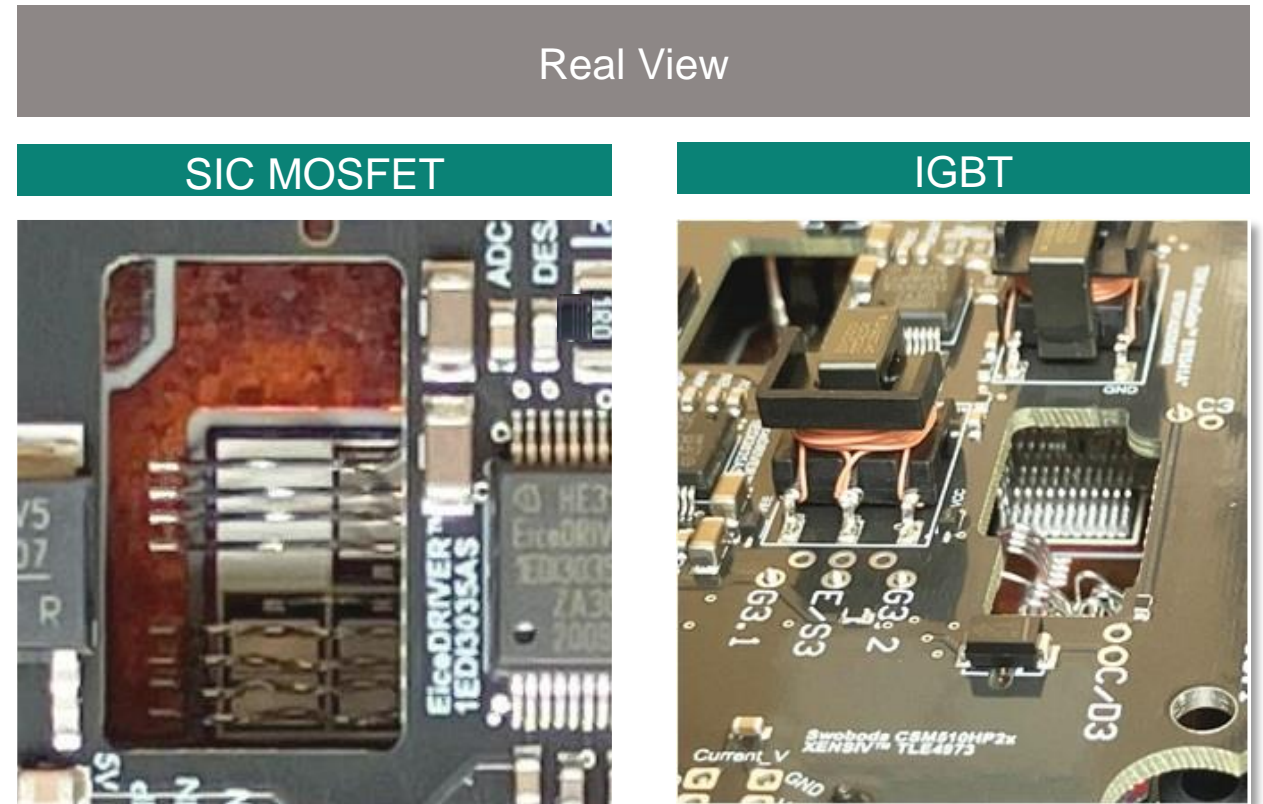
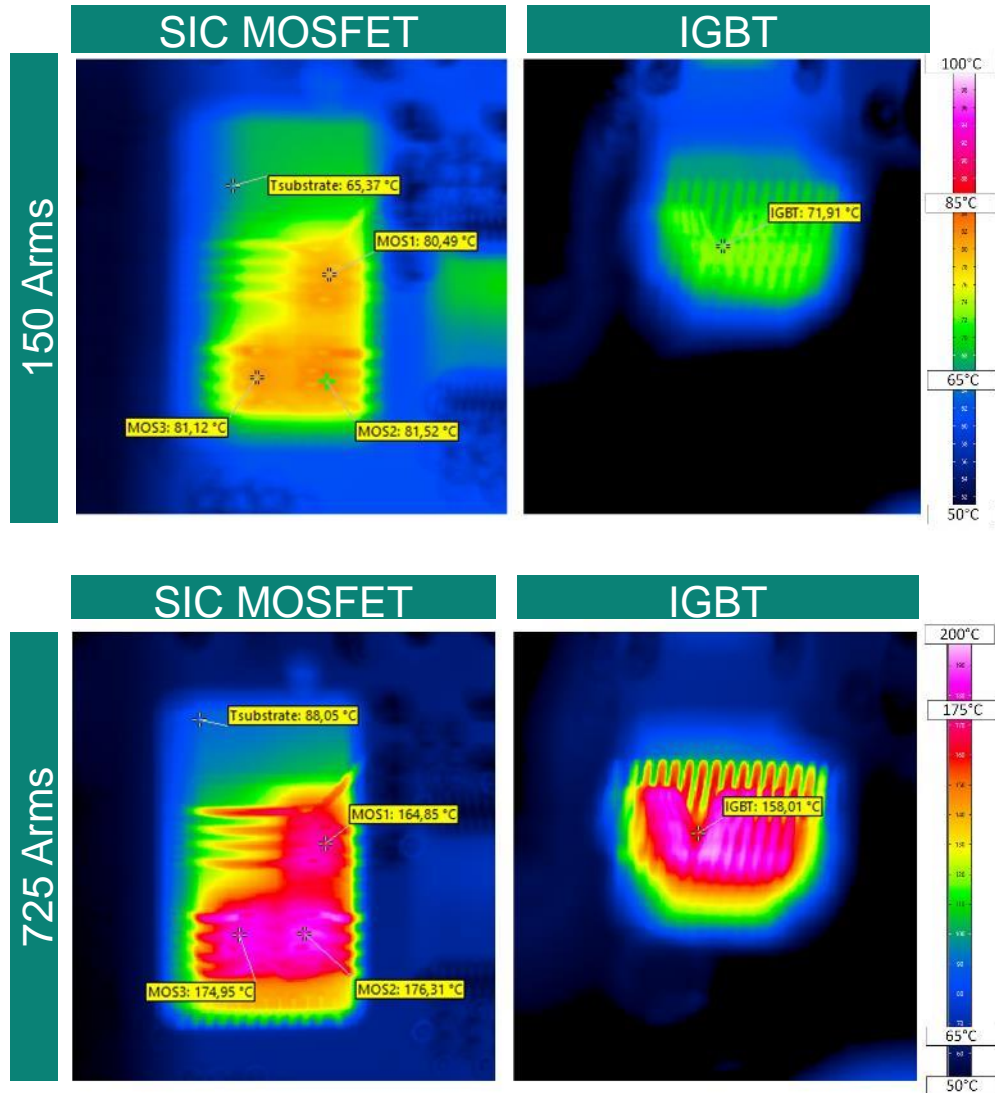
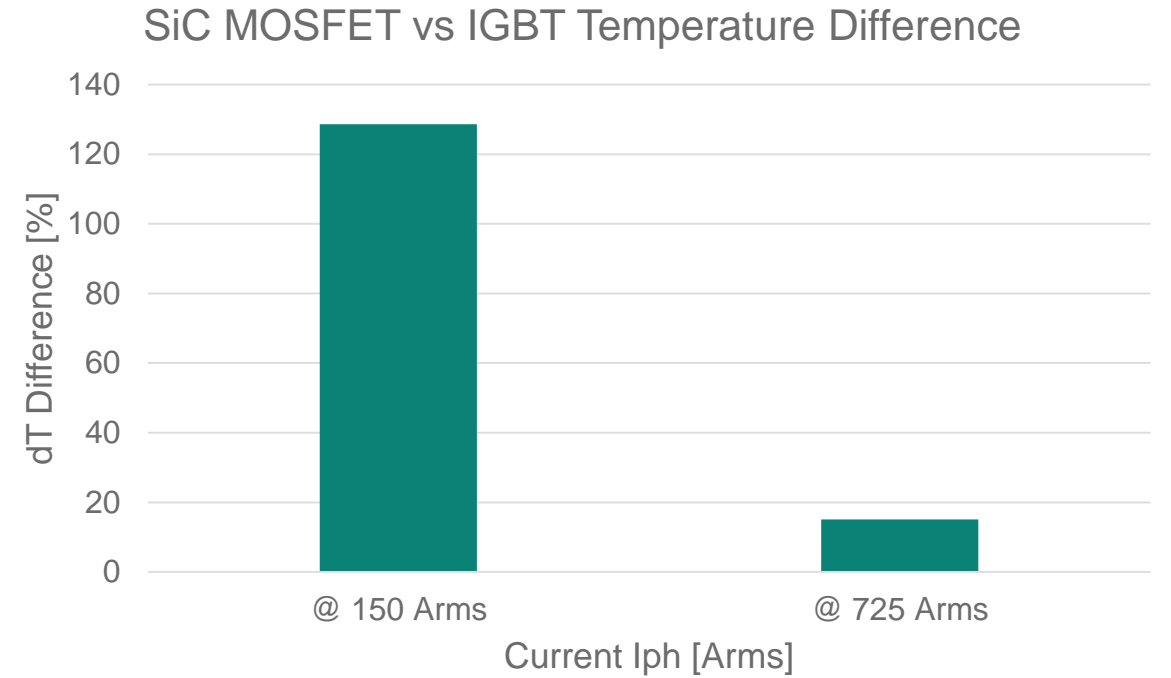
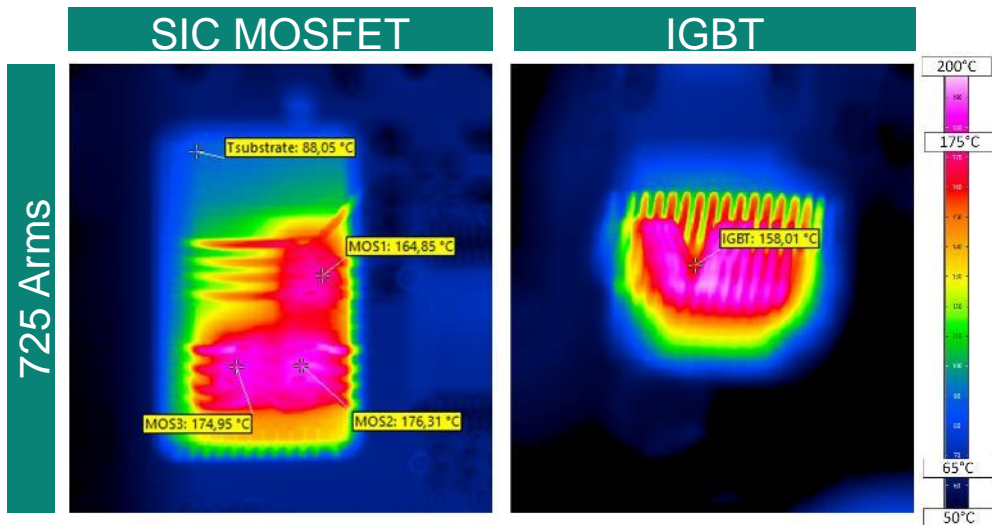
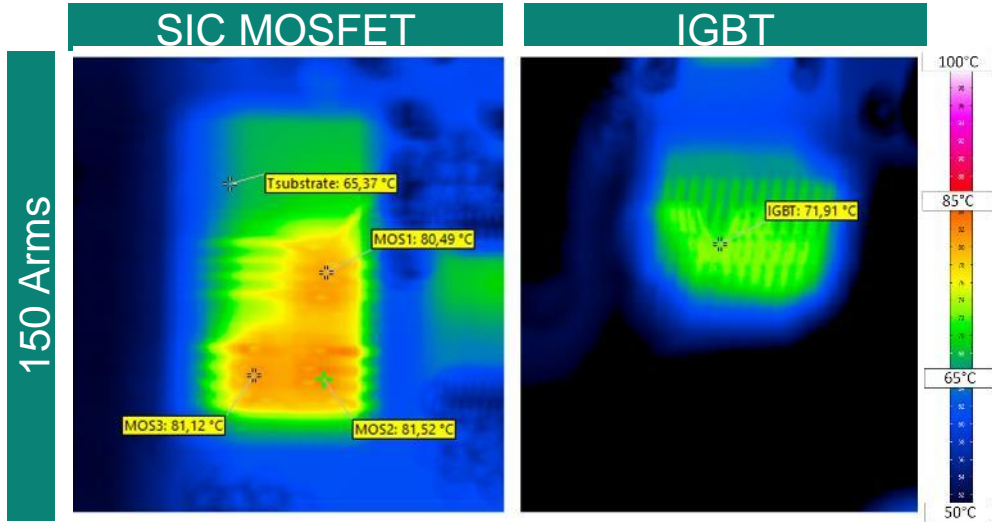


Illustration real view without black paint required for constant IR emission rate

Fusion Switch Concept Thermal Testing

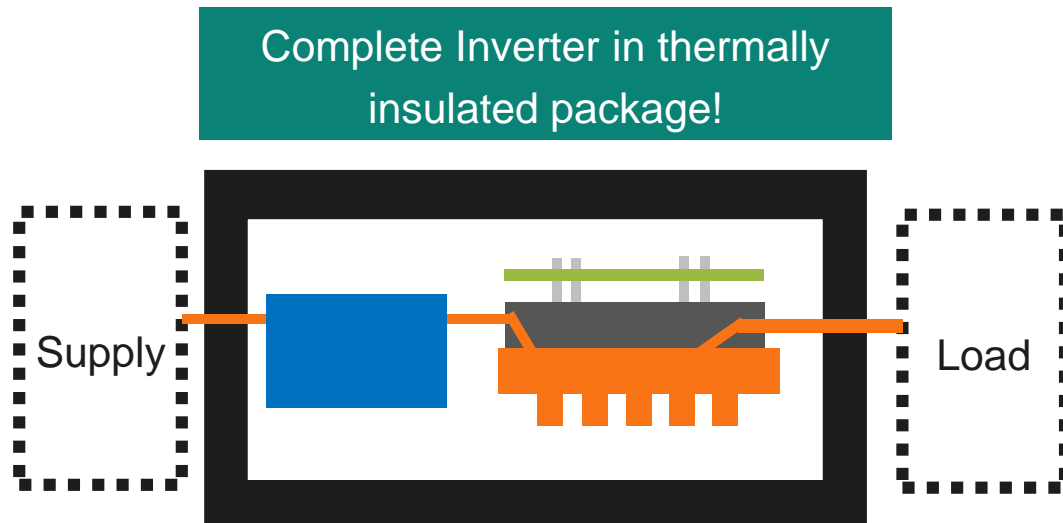
Inverter Thermal IR Testing @400V, 10kHz and 65°C coolant fluid



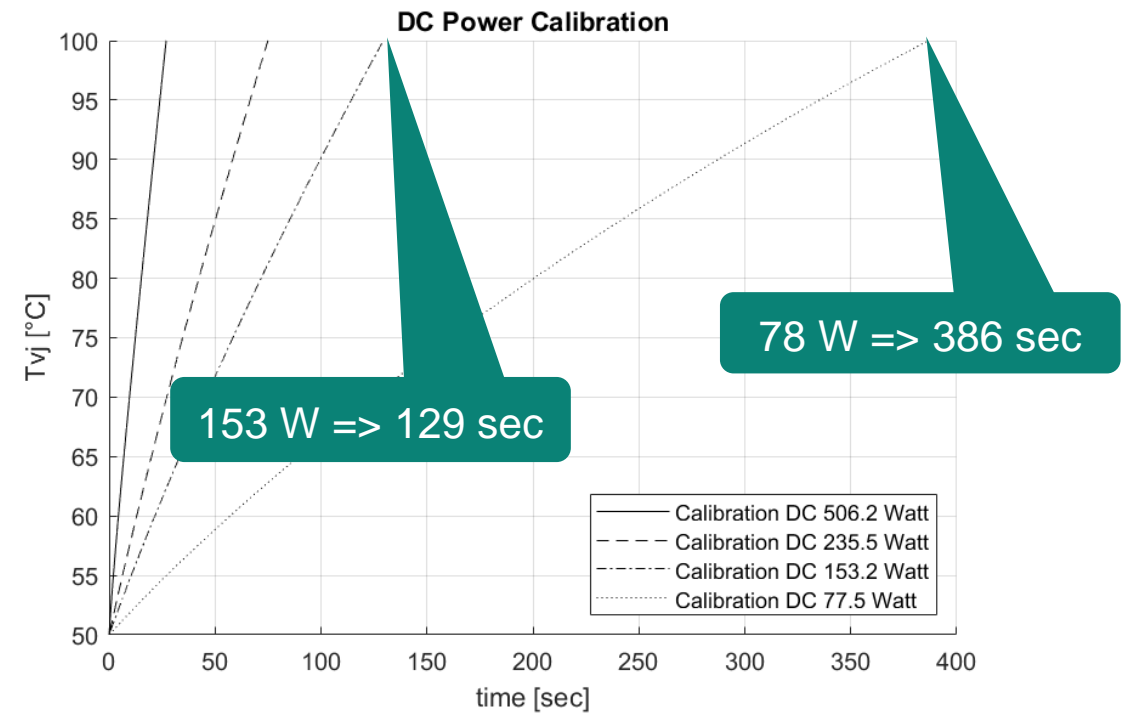
The SiC MOSFET mainly drives the light load currents.

The full load currents are shared on SiC MOSFET and IGBTs for a balanced thermal/electric stress.

Fusion Switch Concept Adiabatic Calorimeter Testing



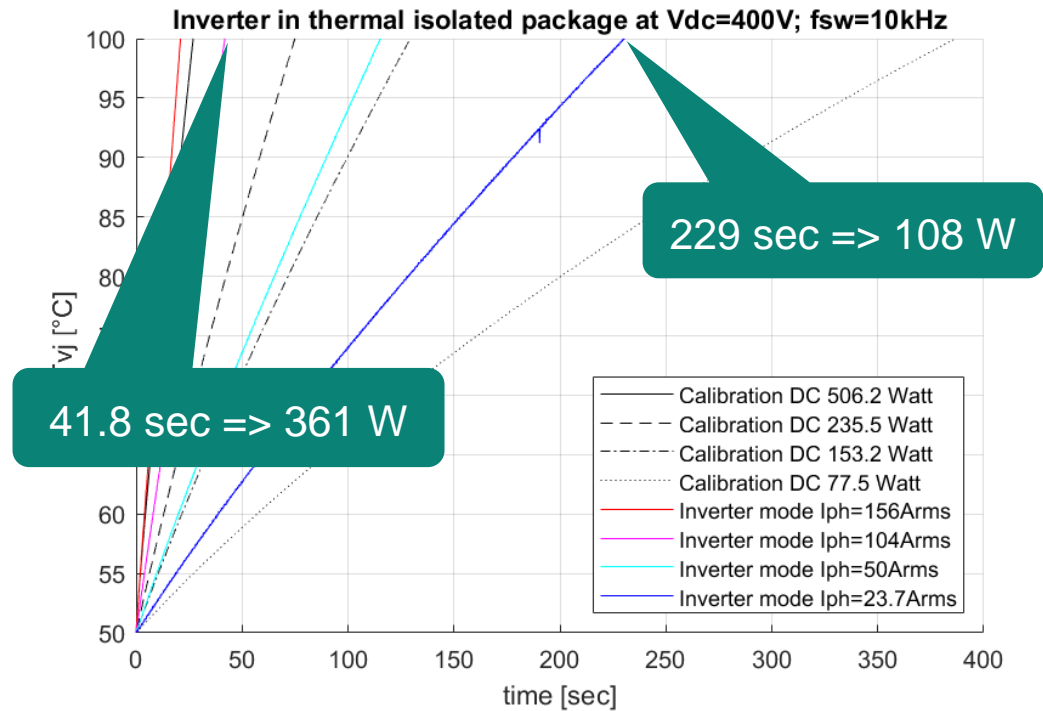
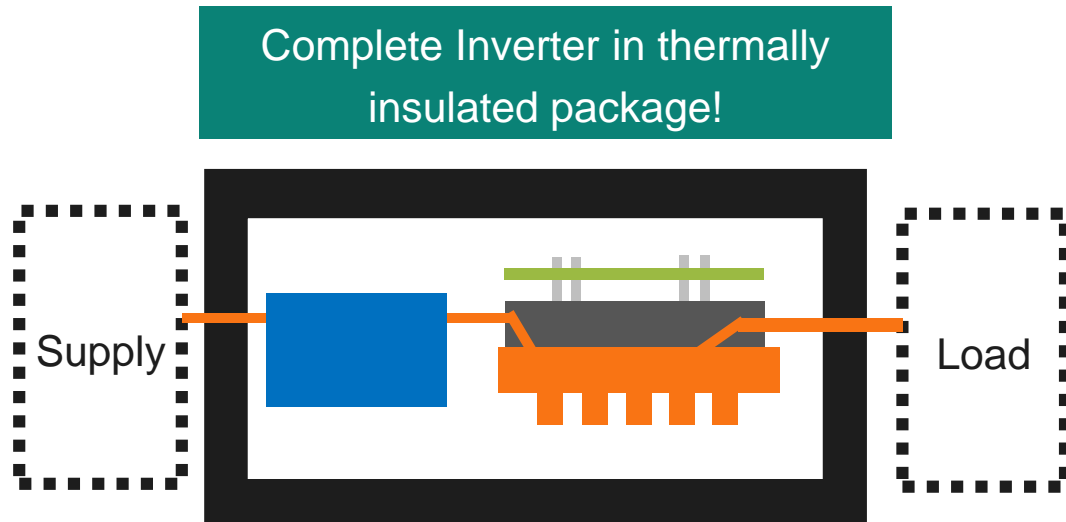
1st Step Calibration:
Supply with DC Power and measure temperature rise within this thermal isolated package.



More detailed information: A. Pai, T. Reiter, O. Vodyakho, M. Maerz, "Mission Profile Analysis of a SiC Hybrid Module for Automotive Traction Inverters and its Experimental Powerloss Validation with Electrical and Calorimetric Methods" in *Advances in Science, Technology and Engineering Systems Journal* Vol. 3, No. 1, 329- 341, 2018.

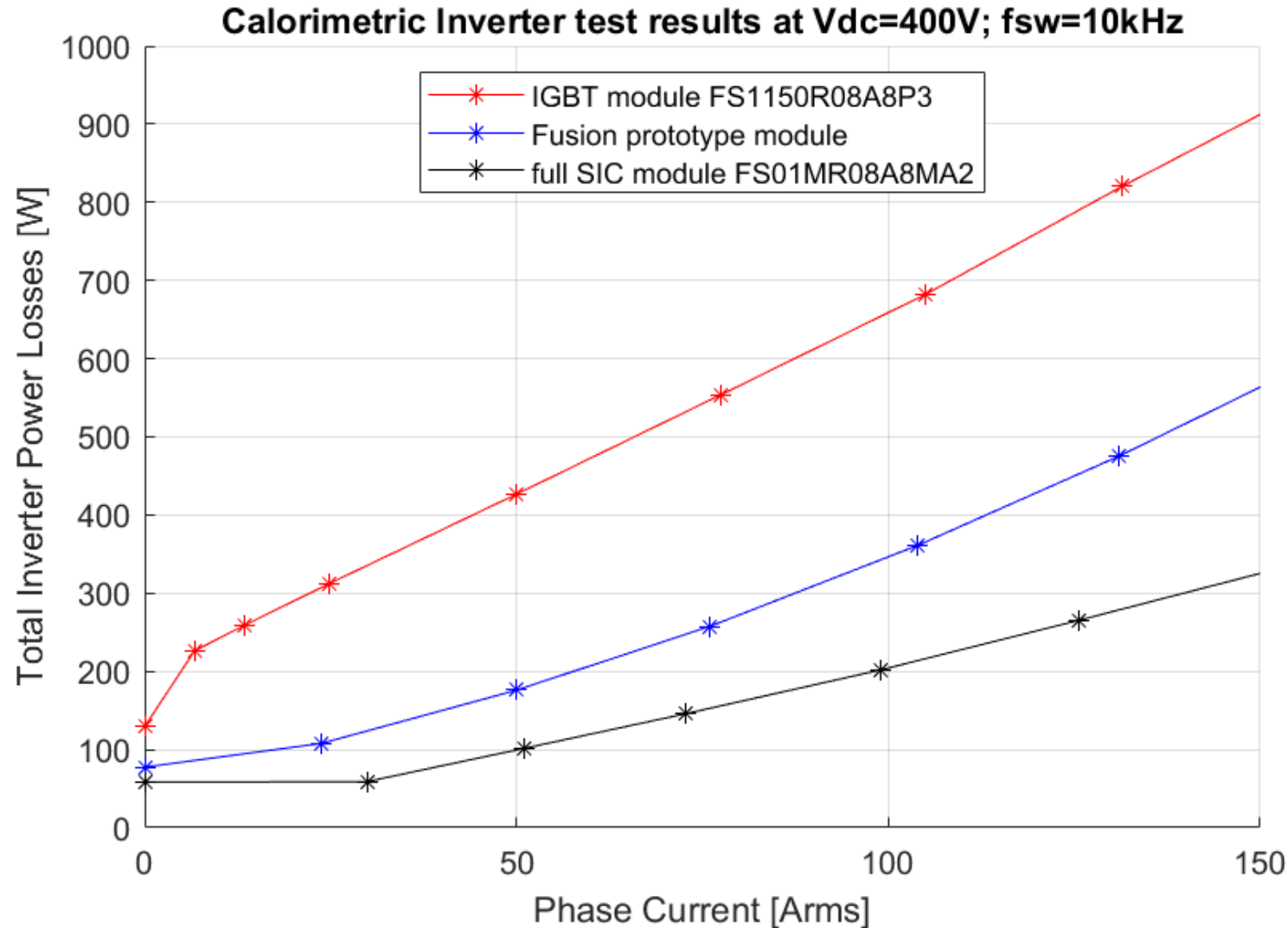
Fusion Switch Concept Adiabatic Calorimeter Testing

2nd Step Inverter Operation:
3rd Step Correlation of Power Losses



More detailed information: A. Pai, T. Reiter, O. Vodyakho, M. Maerz, "Mission Profile Analysis of a SiC Hybrid Module for Automotive Traction Inverters and its Experimental Powerloss Validation with Electrical and Calorimetric Methods" in *Advances in Science, Technology and Engineering Systems Journal* Vol. 3, No. 1, 329- 341, 2018.

Fusion Switch Concept Power Loss Comparison



With just 30% of SiC MOSFET die content we achieve more than 70% of the efficiency gain of a Full SiC MOSFET power module.

Nomenclature:

$$\text{"Efficiency Gain"} = \frac{P_{\text{loss,Fusion}} - P_{\text{loss,IGBT}}}{P_{\text{loss,SiC}} - P_{\text{loss,IGBT}}}$$

Fusion Switch Concept Summary & Conclusion

➤ **Fusion switch addresses the „Cost/Performance Dilemma“ in EV powertrains.**

Just 30% of SiC MOSFET area lead to more than 70% of the efficiency gain of a full SiC MOSFET module.

➤ **Fusion switch can be designed for a simple „Single Gate Drive“.**

The SiC MOSFETs, IGBTs as well as the power module layout can provide the required current sharing.
This reduces customer design efforts and risk.

➤ **The switching slopes are extremely fast & smooth.**

The IGBT/Diodes provide an active „snubber“ effect for the SiC MOSFET chips.
Switching overshoots and oscillations are damped without compromise on switching efficiency.

